

REMARKS


The above amendment is presented to eliminate multiple dependent claims, thereby reducing PTO filing fees.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is entitled "**Version with Markings to Show Changes Made**".

Favorable action on the merits is now requested.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please rewrite claim 4 as follows:

4. (Amended) A separating machine for a thinned semiconductor substrate according to claim 2 [or 3], wherein the system for making a starting point for the separation is a system of pressing with a knife edge.

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